

Excellent Integrated System Limited

Stocking Distributor

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Walsin Technology Corporation RFBPF2012090A1T

For any questions, you can email us directly: sales@integrated-circuit.com

Approval sheet



APPROVAL SHEET

RFBPF 2012(0805) Series — RoHS Compliance

MULTILAYER CERAMIC BAND PASS FILTER

Halogens Free Product

2.4 GHz ISM Band Working Frequency

P/N: RFBPF2012090A2T



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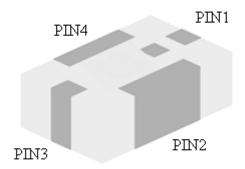
FEATURES

- 1. Miniature footprint: 2.0 X 1.2 X 0.9 mm³
- 2. Low Profile Thickness
- 3. Low Insertion loss
- 4. High Rejection Rate
- 5. High attenuation on 2nd harmonic suppressed
- 6. LTCC process

APPLICATIONS

- 1. 2.4GHz ISM band RF applications
- 2. Bluetooth, Wireless LAN 802.11b/g, HomeRF

CONSTRUCTION



PIN	Connection		
1	Input port		
2	GND		
3	Output port		
4	GND		

Fig 1. Outline of 2.4GHz Band Pass Filter 2012 size

DIMENSIONS

Figure	Symbol	Dimension (mm)
	L	2.00 ± 0.15
	W	1.25± 0.15
· ·	Т	0.90 ± 0.10
A B	А	0.5 ± 0.15
	В	1.0 ± 0.15
	С	0.25 ± 0.15
	D	0.25 ± 0.15
	Е	0.45 ± 0.15
	F	0.35 ± 0.15

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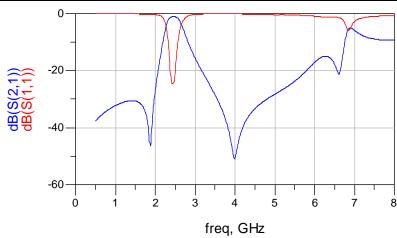


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ELECTRICAL CHARACTERISTICS

RFBPF2012090A2T	Specification
Frequency range	2450 ± 50 MHz
Insertion Loss	1.4 dB max
VSWR	2.0 max
Impedance	50 Ω
Attenuation (min.)	30dB @ 824~960MHz 30dB @ 1710~1910 MHz 20dB @ 1920~1990 MHz 6dB @ 2110~2170MHz 20dB @ 4800~5000 MHz
Operation Temperature Range	-40℃ ~ +85℃

Typical Electrical Chart



SOLDER LAND PATTERN

Figure	Symbol	Dimension (mm)
	L1	1.27 ± 0.10
U V	L2	0.51 ± 0.05
	L3	0.61 ± 0.05
	L4	0.38 ± 0.05
S3 L2	L5	0.51 ± 0.05
W_2 W_3 W_4 U_3 U_4 U_5 U_5 U_5 U_6 U_7 U_8	W1	0.76 ± 0.10
	W2	1.02 ± 0.10
	W3	0.41 ± 0.05
	W4	0.76 ± 0.05
	S1	0.49 ± 0.05
	S2	0.25 ± 0.05
Line width to be design to match 50 Ω characteristic impedance, depending on PCB material and thickness.	S3	0.38 ± 0.05
Φ are the grounding through holes.	Φ	0.41 ± 0.10



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RELIABILITY TEST

Test item	Test condition / Test method	Specification
Solderability JIS C 0050-4.6	*Solder bath temperature : 235 ± 5°C	At least 95% of a surface of each terminal
JESD22-B102D	*Immersion time : 2 ± 0.5 sec	electrode must be covered by fresh solder.
	*Solder : Sn3Ag0.5Cu for lead-free	
Leaching (Resistance to dissolution of metallization) IEC 60068-2-58	*Solder bath temperature : $260 \pm 5^{\circ}\text{C}$ *Leaching immersion time : $30 \pm 0.5 \text{ sec}$ *Solder : SN63A	Loss of metallization on the edges of each electrode shall not exceed 25%.
Resistance to soldering heat JIS C 0050-5.4	*Preheating temperature : 120~150°C, 1 minute. *Solder temperature : 270±5°C *Immersion time : 10±1 sec *Solder : Sn3Ag0.5Cu for lead-free Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage. Samples shall satisfy electrical specification after test. Loss of metallization on the edges of each electrode shall not exceed 25%.
Drop Test JIS C 0044	*Height: 75 cm *Test Surface: Rigid surface of concrete or steel. *Times: 6 surfaces for each units; 2 times for each side.	No mechanical damage. Samples shall satisfy electrical specification after test.
Adhesive Strength of Termination JIS C 0051- 7.4.3	*Pressurizing force : 5N(≦0603) ; 10N(>0603) *Test time : 10±1 sec	No remarkable damage or removal of the termination.
Bending test JIS C 0051- 7.4.1	The middle part of substrate shall be pressurized by means of the pressurizing rod at a rate of about 1 mm/s per second until the deflection becomes 1mm/s and then pressure shall be maintained for 5±1 sec. Measurement to be made after keeping at room temperature for 24±2 hours	No mechanical damage. Samples shall satisfy electrical specification after test.



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Temperature cycle	1. 30±3 minutes at -40°C±3°C,	No mechanical damage.
JIS C 0025		-
	2. 10~15 minutes at room temperature,	Samples shall satisfy electrical
	3. 30±3 minutes at +85°C±3°C,	specification after test.
	4. 10~15 minutes at room temperature,	
	Total 100 continuous cycles	
	Measurement to be made after keeping at	
	room temperature for 24±2 hrs	
Vibration	*Frequency: 10Hz~55Hz~10Hz(1min)	No mechanical damage.
JIS C 0040	*Total amplitude: 1.5mm	Samples shall satisfy electrical specification
	*Test times: 6hrs.(Two hrs each in three	after test.
	mutually perpendicular directions)	
High temperature		No mark spiral damana
JIS C 0021	*Temperature: 85°C±2°C	No mechanical damage.
	*Test duration: 1000+24/-0 hours	Samples shall satisfy electrical specification
	Measurement to be made after keeping at	after test.
	room temperature for 24±2 hrs	
Humidity	*Humidity: 90% to 95% R.H.	No mechanical damage.
(steady conditions)	*Temperature : 40±2°C	Samples shall satisfy electrical specification
JIS C 0022	*Time: 1000+24/-0 hrs.	after test.
	Measurement to be made after keeping at	
	room temperature for 24±2 hrs	
	1000hrs data	
Low temperature	*Temperature : -40°C±2°C	No mechanical damage.
JIS C 0020	*Test duration: 1000+24/-0 hours	Samples shall satisfy electrical specification
	Measurement to be made after keeping at	after test.
	room temperature for 24±2 hrs	
	Toom temperature for 24±2 fils	

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SOLDERING CONDITION

Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2,

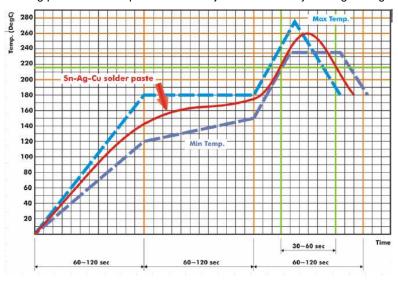


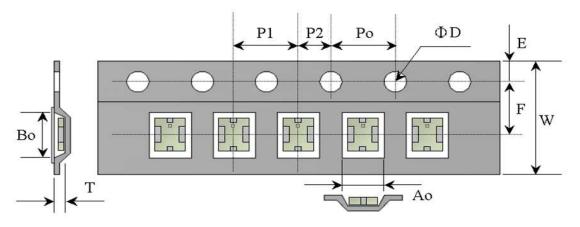
Fig 2. Infrared soldering profile

ORDERING CODE

RF	BPF	201209	0	Α	2	Т
Walsin	Product Code	Dimension code	Unit of	Application	Specification	Packing
RF device	BPF:	Per 2 digits of Length,	dimension	A: 2.4GHZ ISM	Code from 0 ~ 9	T : Reeled
	Band Pass Filter	Width, Thickness:	0 : 0.1 mm	Band	dependent on	
		e.g. :	1 : 1.0 mm		different electrical	
		201209 =				
		Length 20,				
		Width 12,				
		Thickness 09				

Minimum Ordering Quantity: 2000 pcs per reel.

PACKAGING



Plastic Tape specifications (unit :mm)

Index	Ao	Во	ΦD	T	W
Dimension (mm)	1.45 ± 0.10	2.25 ± 0.10	1.55 ± 0.10	1.10 ± 0.10	8.00 ± 0.30
Index	Е	F	Po	P1	P2
Dimension (mm)	1.75± 0.10	3.50 ± 0.05	4.00 ± 0.10	4.00 ± 0.10	2.00± 0.10

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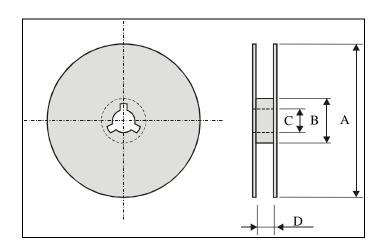
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Reel dimensions



Index	А	В	С
Dimension (mm)	Φ178	Ф60.0	Ф13.5

Taping Quantity:2000 pieces per 7" reel

CAUTION OF HANDLING

Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Disaster prevention / crime prevention equipment
- (6) Traffic signal equipment
- (7) Transportation equipment (vehicles, trains, ships, etc.)
- (8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

Storage condition

- (1) Products should be used in 6 months from the day of WALSIN outgoing inspection, which can be confirmed.
- (2) Storage environment condition.
 - Products should be storage in the warehouse on the following conditions.

■ Temperature : -10 to +40°C

Humidity : 30 to 70% relative humidity

- Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
- Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
- Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
- Products should be storage under the airtight packaged condition.